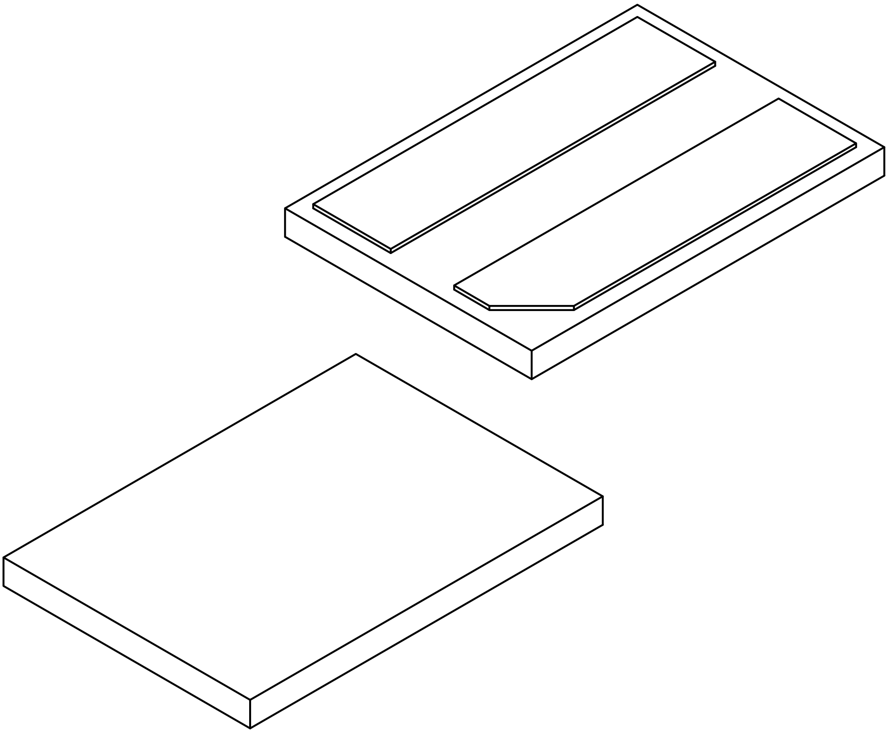
2-Pad Extra-Thin Single Flat, No Lead Package (QJB) - 5x3.5x0.4 mm Body [XSFN] Atmel Legacy GPC YDR

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	MILLIMETERS		
	Dimension Limits	MIN	NOM	MAX
Number of Terminals	N		2	
Pitch	e		2.00 BSC	
Overall Height	A	0.30	0.35	0.40
Standoff	A1	0.00	0.035	0.05
Terminal Thickness	A3		0.127 REF	
Overall Length	D		5.00 BSC	
Overall Width	E		3.50 BSC	
Terminal Width	b	1.05	1.10	1.15
Terminal Length	L	4.55	4.60	4.65
Terminal-to-Terminal	K		0.90 REF	

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M
    BSC: Basic Dimension. Theoretically exact value shown without tolerances.
    REF: Reference Dimension, usually without tolerance, for information purposes only.